

RD Number: RD137

RD Title: TB67S141HG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C1	1	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	
2	C3	1	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	
3	C4	1	100 μ F 50V	–	–	Electrolytic capacitor		
4	C5	0	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	✓
5	C6	0	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	✓
6	C7	0	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	✓
7	C8	0	0.1 μ F 100V	–	–	Chip capacitor	3.2mmX1.6mm	✓
8	R_ERR	1	10k Ω 0.25W	–	–	Chip resistor	3.2mmX1.6mm	
9	R_ALM	1	10k Ω 0.25W	–	–	Chip resistor	3.2mmX1.6mm	
10	R_MO	0	10k Ω 0.25W	–	–	Leaded resistor		✓
11		0	Socket pin	–	–	Socket pin		✓
12	R4	0	Not mount	–	–	Leaded resistor		✓
13		0	Socket pin	–	–	Socket pin		✓
14	R_OSCM	1	10k Ω 0.25W	–	–	Leaded resistor		
15		2	Socket pin	–	–	Socket pin		
16	R_VRF1	1	2.5k Ω 0.25W	–	–	Leaded resistor		
17		2	Socket pin	–	–	Socket pin		
18	R_VRF2	1	2.5k Ω 0.25W	–	–	Leaded resistor		
19		2	Socket pin	–	–	Socket pin		
20	D1	1	CMZ36	CMZ36	TOSHIBA	Zener diode	M-FLAT	
21		0	Pin header 3P	–	–	Jumper		✓
22		0	Jumper socket	–	–	Short pin		✓
23	INA1	1	Pin header 3P	–	–	Jumper		
24		1	Jumper socket	–	–	Short pin		
25	INA2	1	Pin header 3P	–	–	Jumper		

26		1	Jumper socket	-	-	Short pin		
27	INB1	1	Pin header 3P	-	-	Jumper		
28		1	Jumper socket	-	-	Short pin		
29	INB2	1	Pin header 3P	-	-	Jumper		
30		1	Jumper socket	-	-	Short pin		
31	STBY	1	Pin header 3P	-	-	Jumper		
32		1	Jumper socket	-	-	Short pin		
33	BREAK	1	Pin header 3P	-	-	Jumper		
34		1	Jumper socket	-	-	Short pin		
35	JP_VCC	1	Pin header 3P	-	-	Jumper		
36		1	Jumper socket	-	-	Short pin		
37	VCC	1	Check terminal	-	-	Logic pin		
38	ERR	1	Check terminal	-	-	Check pin		
39	ALM	1	Check terminal	-	-	Check pin		
40	PHASEA	1	Check terminal	-	-	Logic pin		
41	PHASEB	1	Check terminal	-	-	Logic pin		
42	INA1	1	Check terminal	-	-	Logic pin		
43	INA2	1	Check terminal	-	-	Logic pin		
44	INB1	1	Check terminal	-	-	Logic pin		
45	INB2	1	Check terminal	-	-	Logic pin		
46	STBY	1	Check terminal	-	-	Logic pin		
47	BREAK	1	Check terminal	-	-	Logic pin		
48	OSCM	1	Check terminal	-	-	Logic pin		
49	VM	1	Check terminal	-	-	Logic pin		
50	VM	1	Check terminal	-	-	Logic pin		
51	VCOM	1	Check terminal	-	-	Logic pin		
52	OUT_A+	1	Check terminal	-	-	Logic pin		
53	OUT_A-	1	Check terminal	-	-	Logic pin		
54	OUT_B-	1	Check terminal	-	-	Logic pin		
55	OUT_B+	1	Check terminal	-	-	Logic pin		
56	VDD	1	Check terminal	-	-	Logic pin		
57	GND	1	Check terminal	-	-	Logic pin		
58	GND	1	Check terminal	-	-	Logic pin		
59	GND	1	Check terminal	-	-	Logic pin		

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